MSP430F2617 Device Erratasheet

1 Revision History

✓ The check mark indicates that the issue is present in the specified revision.

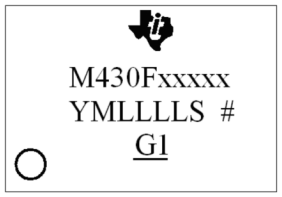
Errata Number	Rev H	Rev F	Rev E	Rev D	Rev B	Rev A
ADC18						✓
ADC19					✓	✓
ADC25	✓	✓	✓	✓	✓	✓
BCL12	✓	✓	✓	✓	✓	✓
BCL13			✓	✓	✓	✓
BCL15	✓	✓	✓	✓	✓	✓
COMP2				✓	✓	✓
CPU8	✓	✓	✓	✓	✓	✓
CPU16	✓	✓	✓	✓	✓	✓
DMA3	✓	✓	✓	✓	✓	✓
DMA4	✓	✓	✓	✓	✓	✓
FLASH19	✓	✓	✓	✓	✓	✓
FLASH22						✓
FLASH23						✓
FLASH24	✓	✓	✓	✓	✓	✓
FLASH25			✓	✓	✓	✓
FLASH27	✓	✓	✓	✓	✓	✓
FLASH36	✓	✓	✓	✓	✓	✓
JTAG23	✓	✓	✓	✓	✓	✓
PORT10	✓	✓	✓	✓	✓	✓
PORT12	✓	✓	✓	✓	✓	✓
SVS2	✓	✓	✓	✓	✓	✓
TA12	✓	✓	✓	✓	✓	✓
TA16	✓	✓	✓	✓	✓	✓
TA21	✓	✓	✓	✓	✓	✓
TAB22	✓	✓	✓	✓	✓	✓
TB2	✓	✓	✓	✓	✓	✓
TB16	✓	✓	✓	✓	✓	✓
TB19						✓
TB24	✓	✓	✓	✓	✓	✓
USCI16						✓
USCI20	✓	✓	✓	✓	✓	✓
USCI21	✓	✓	✓	✓	✓	✓
USCI22	✓	✓	✓	✓	✓	✓
USCI23	✓	✓	✓	✓	✓	✓
USCI24	✓	✓	✓	✓	✓	✓

Errata Number	Rev H	Rev F	Rev E	Rev D	Rev B	Rev A
USCI25	✓	✓	✓	✓	✓	✓
USCI26	✓	✓	✓	✓	✓	✓
USCI27	✓	✓	✓	✓	✓	✓
USCI30	✓	✓	✓	✓	✓	✓
USCI35	✓	✓	✓	✓	✓	✓
XOSC5	✓	✓	✓	✓	✓	✓
XOSC6						✓
XOSC8		✓	✓	✓	✓	✓

2 Package Markings

ZQW113

BGA (ZQW), 113 Pin

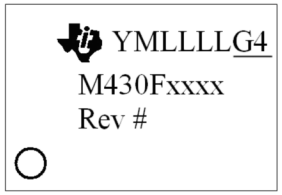


YM = Year and Month Date Code
LLLL = LOT Trace Code
S = Assembly Site Code
# = DIE Revision
o = PIN 1

PN80

LQFP (PN), 80 Pin

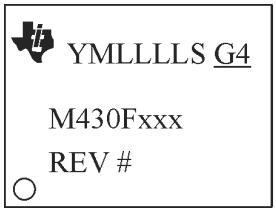
YM = Year and Month Date Code
LLLL = LOT Trace Code
S = Assembly Site Code
# = DIE Revision
o = PIN 1



YM = Year and Month Date Code
LLLL = LOT Trace Code
S = Assembly Site Code
# = DIE Revision
o = PIN 1

PM64

LQFP (PM), 64 Pin



YM = Year and Month Date Code
LLLL = LOT Trace Code
S = Assembly Site Code
# = DIE Revision
○ = Pin 1

3 Detailed Bug Description

ADC18 *ADC12 Module*

Function Incorrect conversion result in extended sample mode

Description The ADC12 conversion result can be incorrect if the extended sample mode is selected (SHP = 0), the conversion clock is not the internal ADC12 oscillator (ADC12SSEL > 0), and one of the following two conditions is true:

- The extended sample input signal SHI is asynchronous to the clock source used for ADC12CLK and the undivided ADC12 input clock frequency exceeds 3.15 MHz.

or

- The extended sample input signal SHI is synchronous to the clock source used for ADC12CLK and the undivided ADC12 input clock frequency exceeds 6.3 MHz.

Workaround

- Use the pulse sample mode (SHP = 1).

or

- Use the ADC12 internal oscillator as the ADC12 clock source.

or

- Limit the undivided ADC12 input clock frequency to 3.15 MHz.

or

- Use the same clock source (such as ACLK or SMCLK) to derive both SHI and ADC12CLK, to achieve synchronous operation, and also limit the undivided ADC12 input clock frequency to 6.3 MHz.

ADC19 *ADC12 Module*

Function Sample start in extended pulse mode

Description When operating in extended pulse mode, if ADC12SC is set in the same instruction as the first setting of ENC, a sample is not started (that is, the ADC12SC bit has no effect). Instead, ENC must be set at least one instruction prior to the first occurrence of ADC12SC being set.

Workaround Set ENC in a separate instruction prior to setting ADC12SC.

ADC25 *ADC12 Module*

Function Write to ADC12CTL0 triggers ADC12 when CONSEQ = 00

Description If ADC conversions are triggered by the Timer_B module and the ADC12 is in single-channel single-conversion mode (CONSEQ = 00), ADC sampling is enabled by write access to any bit(s) in the ADC12CTL0 register. This is contrary to the expected behavior that only the ADC12 enable conversion bit (ADC12ENC) triggers a new ADC12 sample.

Workaround When operating the ADC12 in CONSEQ=00 and a Timer_B output is selected as the sample and hold source, temporarily clear the ADC12ENC bit before writing to other bits in the ADC12CTL0 register. The following capture trigger can then be re-enabled by setting ADC12ENC = 1.

BCL12 *BCS Module*

Function Switching RSELx or modifying DCOCTL can cause DCO dead time or a complete DCO stop

Description After switching RSELx bits (located in register BCSCTL1) from a value of >13 to a value of <12 OR from a value of <12 to a value of >13, the resulting clock delivered by the DCO can stop before the new clock frequency is applied. This dead time is approximately 20 us. In some instances, the DCO may completely stop, requiring a power cycle.

Furthermore, if all of the RSELx bits in the BSCTL1 register are set, modifying the DCOCTL register to change the DCOx or the MODx bits could also result in DCO dead time or DCO hang up.

Workaround - When switching RSEL from >13 to <12, use an intermediate frequency step. The intermediate RSEL value should be 13.

Current RSEL	Target RSEL	Recommended Transition Sequence
15	14	Switch directly to target RSEL
14 or 15	13	Switch directly to target RSEL
14 or 15	0 to 12	Switch to 13 first, and then to target RSEL (two step sequence)
0 to 13	0 to 12	Switch directly to target RSEL

AND

- When switching RSEL from <12 to >13 it's recommended to set RSEL to its default value first (RSEL = 7) before switching to the desired target frequency.

AND

- In case RSEL is at 15 (highest setting) it's recommended to set RSEL to its default value first (RSEL = 7) before accessing DCOCTL to modify the DCOx and MODx bits. After the DCOCTL register modification the RSEL bits can be manipulated in an additional step.

In the majority of cases switching directly to intermediate RSEL steps as described above will prevent the occurrence of BCL12. However, a more reliable method can be implemented by changing the RSEL bits step by step in order to guarantee safe function without any dead time of the DCO.

Note that the 3-step clock startup sequence consisting of clearing DCOCTL, loading the BCSCTL1 target value, and finally loading the DCOCTL target value as suggested in the in the "TLV Structure" chapter of the MSP430x2xx Family User's Guide is not affected by BCL12 if (and only if) it is executed after a device reset (PUC) prior to any other modifications being made to BCSCTL1 since in this case RSEL still is at its default value of 7. However any further changes to the DCOx and MODx bits will require the consideration of the workaround outlined above.

BCL13 *BCS Module*

Function DCO powerup halt

Description When subject to very slow Vcc rise times, the device may enter into a state where the DCO does not oscillate. No JTAG access or program execution is possible and the device will remain in a reset state until the supply voltage is disconnected.

Workaround Apply a Vcc poweron ramp >= 10V/second under all power-on/power-cycle scenarios.

BCL15 *BCS Module*

Function Unpredictable LPM3 wake-up behavior if MCLK sourced by XT2

Description If the MCLK is sourced by the XT2 oscillator, when the device wakes up from LPM3 an unpredictable glitch might appear causing the device to hang up or execute code incorrectly.

Workaround 1. Do not use XT2 clock for MCLK when using LPM3

OR

2. Use a clock divider for MCLK.

COMP2 *COMP_A Module*

Function Configuring the port disable register (CAPD)

Description According to the user's guide, each bit in the CAPD register should correspond with its associated port I/O number. For example, when "bit 0" of CAPD is set, the port disable function of pin Px.0 is enabled; "bit 1" controls Px.1, and so on (where Px is the port that contains the comparator inputs). However, on this device, the bits of the CAPD register correspond with the Comparator_A input number. For example, "bit 0" of CAPD controls the CA0 input, "bit 1" controls CA1, etc. This difference matters when the port I/O number is not the same as the comparator input number.

If the wrong CAPD bit is set, the port I/O function for the wrong pin will be disabled. Also, the analog signal applied to the comparator input pin being used may cause a parasitic current to flow from Vcc to GND. See the Comparator_A+ chapter of the MSP430x2xx Family User's Guide (SLAU144) for more information on CAPD.

Workaround None

CPU8 *CPUX Module*

Function Using odd values in the SP register

Description The SP can be written with odd values. In the original CPU, an odd SP value could be combined with an odd offset (for example, mov. #value, 5(SP)). In the new CPU, the SP can be written with an odd value, but the first time the SP is used, the LSB is forced to 0.

Workaround Do not use odd values with the SP.

CPU16 *CPUX Module*

Function Indexed addressing with instructions calla, mova and bra.

Description With indexed addressing mode and instructions calla, mova, and bra, it is not possible to reach memory above 64k if the register content is < 64k.

Example: Assume R5 = FFFEh. The instruction calla 0004h(R5) will result in a 20-bit call of address 0002h instead of 10002h.

Workaround - Use different addressing mode to reach memory above 64k.

- First use adda [index],[Rx] to calculate address in upper memory and then do a calla [Rx]

DMA3 *DMA Module*

Function Read-modify-write instructions may corrupt DMA address registers

Description When a 16-bit wide read-modify-write instruction (such as add.w and sub.w) is directly used on a DMA address register (DMAxSA or DMAxDA), the register contents will get corrupted.

Workaround 1. Do not use 16-bit wide read-modify-write instructions on DMA address registers. Instead, in case address calculations are necessary, do the calculations first, and then assign the result to the DMA address registers.

OR

2. Use 20-bit wide read-modify-write instructions (such as addx.a, subx.a) on the DMA address registers if needed.

DMA4 *DMA Module*

Function Corrupted write access to 20-bit DMA registers

Description When a 20-bit wide write to a DMA address register (DMAxSA or DMAxDA) is interrupted by a DMA transfer, the register contents may be unpredictable.

Workaround 1. Design the application to guarantee that no DMA access interrupts 20-bit wide accesses to the DMA address registers.

OR

2. When accessing the DMA address registers, enable the Read Modify Write disable bit (DMARMWDIS = 1) or temporarily disable all active DMA channels (DMAEN = 0).

OR

3. Use word access for accessing the DMA address registers. Note that this limits the values that can be written to the address registers to 16-bit values (lower 64K of Flash).

FLASH19 *FLASH Module*

Function EEI feature does not work for code execution from RAM

Description When the program is executed from RAM, the flash controller EEI feature does not work. The erase cycle is suspended and the interrupt is serviced, but there is a problem while resuming with the erase cycle.

Addresses applied to flash are different than the actual values while resuming erase cycle after ISR execution.

Workaround None

FLASH22 *FLASH Module*

Function Flash controller may prevent correct LPM entry

Description When ACLK (or SMCLK) is used as the flash controller clock source, and this clock source gets deactivated due to a low-power mode entry while a flash erase or write operating is pending, the flash controller will keep ACLK (or SMCLK) active even after the flash operation has been completed. This will result in an incorrect LPM entry and increased current consumption. Note that this issue can only occur when the Flash

operation and the low-power mode entry are initiated from code located in RAM.

Workaround Do not enter low-power modes while flash erase or write operations are active. Wait for the operation to be completed before entering a low-power mode.

FLASH23 *FLASH Module*

Function Erasing flash memory

Description The option to erase all main memory segments (MERAS=1, ERASE=0) does not apply to the entire main memory area. Flash arrays below and above the 64k address boundary must be erased separately.

Workaround Erase each main memory segment separately.

FLASH24 *FLASH Module*

Function Write or erase emergency exit can cause failures

Description When a flash write or erase is abruptly terminated, the following flash accesses by the CPU may be unreliable resulting in erroneous code execution. The abrupt termination can be the result of one the following events:

1) The flash controller clock is configured to be sourced by an external crystal. An oscillator fault occurs thus stopping this clock abruptly.

or

2) The Emergency Exit bit (EMEX in FCTL3) when set forces a write or an erase operation to be terminated before normal completion.

or

3) The Enable Emergency Interrupt Exit bit (EEIEX in FCTL1) when set with GIE=1 can lead to an interrupt causing an emergency exit during a Flash operation.

Workaround 1) Use the internal DCO as the flash controller clock provided from MCLK or SMCLK.

or

2) After setting EMEX = 1, wait for a sufficient amount of time before Flash is accessed again.

or

3) No Workaround. Do not use EEIEX bit.

FLASH25 *FLASH Module*

Function Marginal Read Mode is not functional

Description The control bits for marginal read mode contained in the FCTL4 register are automatically cleared by any flash access. This prevents the marginal read mode from being used.

Workaround It is possible to read out memory contents in marginal read mode if the indexed addressing mode X(Ry) is used to access the flash memory. In this case, the FCTL4 control bits are not cleared, and the marginal read mode works as expected. It is recommended to write the code for reading the flash memory contents in assembler as

this allows full control over the used addressing mode. Note that certain assemblers may optimize an indexed addressing source operation of 0(Ry) to an indirect register mode @Ry operation, which will not work. The following is an example of reading the word memory location 0x4000 in marginal read mode, preventing a possible assembler optimization:

mov.w #0x4000,R15 ; Pointer to target address

dec.w R15 ; Decrement pointer

mov.w 1(R15),R12 ; Read memory contents at R15+1, store result in R12

FLASH27 *FLASH Module*

Function EEI feature can disrupt segment erase

Description When a flash segment erase operation is active with EEI feature selected (EEI=1 in FLCTL1) and GIE=0, the following can occur:

An interrupt event causes the flash erase to be stopped, and the flash controller expects an RETI to resume the erase. Because GIE=0, interrupts are not serviced and RETI will never happen.

Workaround 1) Do not set bit EEI=1 when GIE = 0.

or,

2) Force an RETI instruction during the erase operation during the check for BUSY=1 (FCLTL3).

Sample code:

MOV R5, 0(R5) ; Dummy write, erase segment

LOOP: BIT #BUSY, &FCTL3 ; test busy bit

JMP SUB_RETI ; Force RETI instruction

JNZ LOOP ; loop while BUSY=1

SUB_RETI: PUSH SR

RETI

FLASH36 *FLASH Module*

Function Flash content may degrade due to aborted page erases

Description If a page erase is aborted by EEIEX, the flash page containing the last instruction before erase operation will start to degrade. This effect is incremental and, after repetitions, may lead to corrupted flash content.

Workaround - Use the EEI (interrupted erasing) feature instead of EEIEX (abort erasing).

or

- A PSA checksum can be calculated over affected flash page using the marginal read mode (marginal 0). If PSA sum differs from expected PSA value the affected flash page has to be reprogrammed.

or

- Start flash erasing from RAM and limit system frequency to <1MHz (to ensure 6-us delay after EEIEX). If the last instruction before erasing is located in RAM, flash cell degradation does not occur.

JTAG23 *JTAG Module*

Function PSA checksum calculation does not work in marginal read mode.

Description If the PSA checksum is calculated via JTAG interface in marginal read mode the MRG0 and MRG1 bits in the FCTL4 register are reset.

Workaround None.

PORT10 *PORT Module*

Function Pull-up/down resistor selection when module pin function is selected

Description When the pull-up/down resistor for a certain port pin is enabled (PxREN.y=1) and the module port pin function is selected (PxSEL.y=1), the pull-up/down resistor configuration of this pin is controlled by the respective module output signal (Module X OUT) instead of the port output register (PxOUT.y).

Workaround None. Do not set PxSEL.y and PxREN.y at the same time.

PORT12 *PORT Module*

Function PxIFG is set on PUC

Description The PxIN register is cleared when a PUC is asserted, and it regains the original value after the PUC is de-asserted. If the PxIN register bits read high, asserting a PUC causes clearing of the register, which results in a high-to-low transition. Once the PUC is de-asserted, the PxIN register is restored to high, which results in a low-to-high transition. This behavior results in the PxIFG being set regardless of the PxIES setting.

Workaround Prior to setting PxIE bits ensure that corresponding PxIFG bits are cleared.

SVS2 *SVS Module*

Function DAC1 overwrites an input of the SVS comparator

Description DAC1 overrides the input of the SVS comparator. This is caused by a conflict between SVS and DAC1 at Port 6.7. DAC1 is enabled when DAC12AMPx is > 0.

Workaround Do not enable DAC1 when SVS is used.

TA12 *TIMER_A Module*

Function Interrupt is lost (slow ACLK)

Description Timer_A counter is running with slow clock (external TACLK or ACLK)compared to MCLK. The compare mode is selected for the capture/compare channel and the CCRx register is incremented by one with the occurring compare interrupt (if TAR = CCRx). Due to the fast MCLK the CCRx register increment (CCRx = CCRx+1) happens before the Timer_A counter has incremented again. Therefore the next compare interrupt should happen at once with the next Timer_A counter increment (if TAR = CCRx + 1). This interrupt gets lost.

Workaround Switch capture/compare mode to capture mode before the CCRx register increment. Switch back to compare mode afterwards.

TA16 *TIMER_A Module*

Function First increment of TAR erroneous when IDx > 00

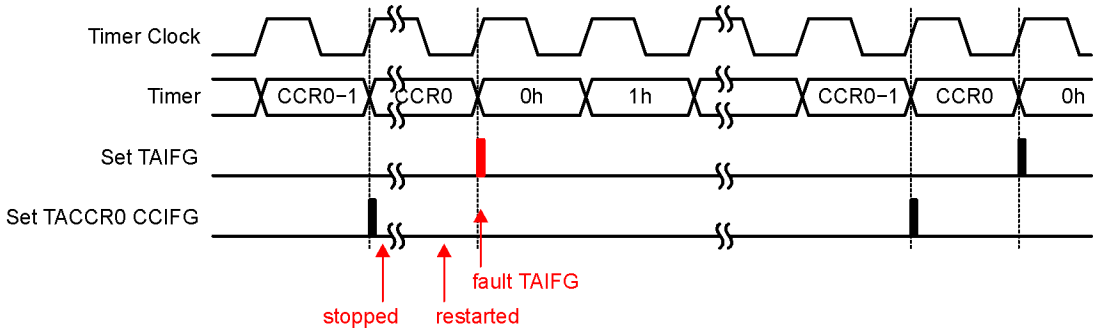
Description The first increment of TAR after any timer clear event (POR/TACLR) happens immediately following the first positive edge of the selected clock source (INCLK, SMCLK, ACLK or TACLK). This is independent of the clock input divider settings (ID0, ID1). All following TAR increments are performed correctly with the selected IDx settings.

Workaround None

TA21 *TIMER_A Module*

Function TAIFG Flag is erroneously set after Timer A restarts in Up Mode

Description In Up Mode, the TAIFG flag should only be set when the timer resets from TACCR0 to zero. However, if the Timer A is stopped at TAR = TACCR0, then cleared (TAR=0) by setting the TACLR bit, and finally restarted in Up Mode, the next rising edge of the TACLK will erroneously set the TAIFG flag.



Workaround None.

TAB22 *TIMER_A/TIMER_B Module*

Function Timer_A/Timer_B register modification after Watchdog Timer PUC

Description Unwanted modification of the Timer_A/Timer_B registers TACTL/TBCTL and TAIV/TBIV can occur when a PUC is generated by the Watchdog Timer(WDT) in Watchdog mode and any Timer_A/Timer_B counter register TACCRx/TBCCRx is incremented/decremented (Timer_A/Timer_B does not need to be running).

Workaround Initialize TACTL/TBCTL register after the reset occurs using a MOV instruction (BIS/BIC may not fully initialize the register). TAIV/TBIV is automatically cleared following this initialization.

Example code:

MOV.W #VAL, &TACTL

or

MOV.W #VAL, &TBCTL

Where, VAL=0, if Timer is not used in application otherwise, user defined per desired function.

TB2 *TIMER_B Module*

Function Interrupt is lost (slow ACLK)

Description Timer_B counter is running with slow clock (external TBCLK or ACLK) compared to MCLK. The compare mode is selected for the capture/compare channel and the CCRx register is incremented by 1 with the occurring compare interrupt (if TBR = CCRx).

Due to the fast MCLK, the CCRx register increment (CCRx = CCRx + 1) happens before the Timer_B counter has incremented again. Therefore, the next compare interrupt should happen at once with the next Timer_B counter increment (if TBR = CCRx + 1). This interrupt is lost.

Workaround Switch capture/compare mode to capture mode before the CCRx register increment. Switch back to compare mode afterward.

TB16 *TIMER_B Module*

Function First increment of TBR erroneous when IDx > 00

Description The first increment of TBR after any timer clear event (POR/TBCLR) happens immediately following the first positive edge of the selected clock source (INCLK, SMCLK, ACLK, or TBCLK). This is independent of the clock input divider settings (ID0, ID1). All following TBR increments are performed correctly with the selected IDx settings.

Workaround None

TB19 *TIMER_B Module*

Function TBIFG/TBIV not updated after access to TBIV

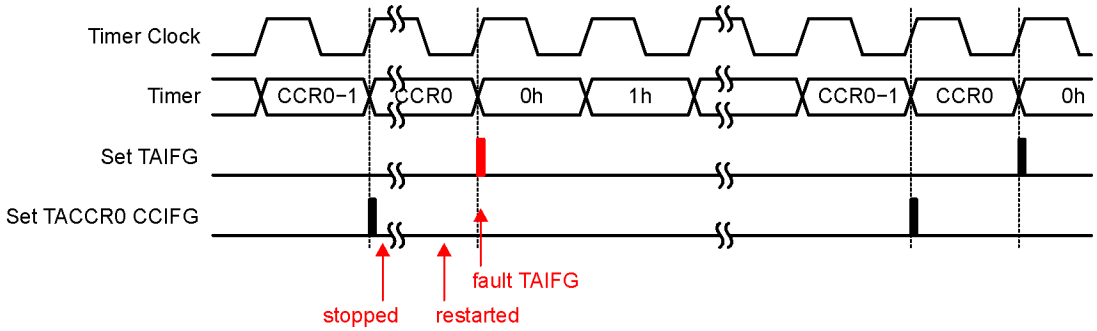
Description After any access to TBIV, the TBIFG flag should automatically be cleared and the TBIV value should be updated to reflect the new state of Timer_B interrupts. However, they are not updated.

Workaround None

TB24 *TIMER_B Module*

Function TBIFG Flag is erroneously set after Timer B restarts in Up Mode

Description In Up Mode, the TBIFG flag should only be set when the timer resets from TBCCR0 to zero. However, if the Timer A is stopped at TBR = TBCCR0, then cleared (TBR=0) by setting the TBCLR bit, and finally restarted in Up Mode, the next rising edge of the TBCLK will erroneously set the TBIFG flag.



Workaround None.

USCI16 *USCI Module*

Function UART/IrDA Mode Lost Characters

Description When configured for UART/IrDA mode, the USCI baud rate generator may halt operation under the following conditions:

1 - IrDA mode: repeated invalid start bits on the receive line

or

2 - UART/IrDA modes: positive pulse on the receive line during break character reception inside the stop bit time slot (the second stop bit time slot in case of UCSPB=1) with a pulse width that passes the deglitch filter but is shorter than half a bit time.

After halting, additional characters will be ignored. Transmit functionality is not affected.

Workaround Check the UCBUSY flag status periodically in software. If the flag is set and no character has been received in the expected time, reset the USCI module in software. To reset the USCI module, toggle UCSWRST and re-enable the USCI interrupts.

USCI20 *USCI Module*

Function I2C Mode Multi-master transmitter issue

Description When configured for I2C master-transmitter mode, and used in a multi-master environment, the USCI module can cause unpredictable bus behavior if all of the following four conditions are true:

1 - Two masters are generating SCL

And

2 - The slave is stretching the SCL low phase of an ACK period while outputting NACK on SDA

And

3 - The slave drives ACK on SDA after the USCI has already released SCL, and then the SCL bus line gets released

And

4 - The transmit buffer has not been loaded before the other master continues communication by driving SCL low

The USCI will remain in the SCL high phase until the transmit buffer is written. After the transmit buffer has been written, the USCI will interfere with the current bus activity and

may cause unpredictable bus behavior.

Workaround

1 - Ensure that slave doesn't stretch the SCL low phase of an ACK period

Or

2 - Ensure that the transmit buffer is loaded in time

Or

3 - Do not use the multi-master transmitter mode

USCI21 *USCI Module*

Function

UART IrDA receive filter

Description

The IrDA receive filter can be used to filter pulses with length UCAIRRXFL configured in UCAxIRRCTL register. If UCIRRXFE is set the IrDA receive decoder may filter out pulses longer than the configured filter length depending on frequency of BRCLK. This is resulting in framing errors or corrupted data on the receiver side.

Workaround

Depending on the used baud rate and the configured filter length a maximum frequency for BRCLK needs to be set to avoid this issue:

For baud rates equal and higher than 115.000 the maximum allowed BRCLK frequency is equal to the max specified system frequency.

$$\text{Max BRCLK} = \frac{\text{Filter Length} + 64}{2} \times \frac{\text{Baud Rate} \times 16}{3 \times 10^6}$$

Baud Rate	Filter Length UCIRRXFL (dec)	Max BRCLK (MHz)
9600	64	3.28
	32	2.46
	16	2.05
	8	1.84
	4	1.74
	2	1.69
	1	1.66
	0	1.64
19200	64	6.55
	32	4.92
	16	4.1
	8	3.69
	4	3.48
	2	3.38
	1	3.33
	0	3.28
38400	64	13.11
	32	9.83
	16	8.19
	8	7.37
	4	6.96
	2	6.76
	1	6.66
	0	6.55
56000	64	19.11
	32	14.34
	16	11.95
	8	10.75
	4	10.15
	2	9.86
	1	9.71
	0	9.56

USCI22 *USCI Module*

Function I2C Master Receiver with 10-bit slave addressing

Description Unexpected behavior of the USCI_B can occur when configured in I2C master receive mode with 10-bit slave addressing under the following conditions:

1) The USCI sends first byte of slave address, the slave sends an ACK and when second address byte is sent, the slave sends a NACK.

2) Master sends a repeat start condition (If UCTXSTT=1).

3) The first address byte following the repeated start is acknowledged.

However, the second address byte is not sent, instead the Master incorrectly starts to receive data and sets UCBxRXIFG=1.

Workaround Do not use repeated start condition instead set the stop condition UCTXSTP=1 in the NACK ISR prior to the following start condition (USTXSTT=1).

USCI23 *USCI Module*

Function UART transmit mode with automatic baud rate detection

Description Erroneous behavior of the USCI_A can occur when configured in UART transmit mode with automatic baud rate detection. During transmission if a "Transmit break" is initiated (UCTXBRK=1), the USCI_A will not deliver a stop bit of logic high, instead, it will send a logic low during the subsequent synch period.

Workaround 1) Follow User's Guide instructions for transmitting a break/synch field following UCSWRST=1.

Or,

2) Set UCTXBRK=1 before an active transmission, i.e. check for bit UCBUSY=0 and then set UCTXBRK=1.

USCI24 *USCI Module*

Function Incorrect baud rate information during UART automatic baud rate detection mode

Description Erroneous behavior of the USCI_A can occur when configured in UART mode with automatic baud rate detection. After automatic baud rate measurement is complete, the UART updates UCAxBR0 and UCAxBR1. Under Oversampling mode (UCOS16=1), for baud rates that should result in UCAxBRx=0x0002, the UART incorrectly reports it as UCAxBRx=0x5555.

Workaround When break/synch is detected following the automatic baud rate detection, the flag UCBRK flag is set to 1. Check if UCAxBRx=0x5555 and correct it to 0x0002.

USCI25 *USCI Module*

Function TXIFG is not reset when NACK is received in I2C mode

Description When the USCI_B module is configured as an I2C master transmitter the TXIFG is not reset after a NACK is received if the master is configured to send a restart (UCTXSTT=1 & UCTXSTP=0).

Workaround Reset TXIFG in software within the NACKIFG interrupt service routine

USCI26 *USCI Module*

Function Tbuf parameter violation in I2C multi-master mode

Description In multi-master I2C systems the timing parameter Tbuf (bus free time between a stop condition and the following start) is not guaranteed to match the I2C specification of 4.7us in standard mode and 1.3us in fast mode. If the UCTXSTT bit is set during a running I2C transaction, the USCI module waits and issues the start condition on bus release causing the violation to occur.

Note: It is recommended to check if UCBBUSY bit is cleared before setting UCTXSTT=1.

Workaround None

USCI27 *USCI Module*

Function Timing of USCI I2C interrupts may cause device reset due to automatic clear of an IFG.

Description When certain USCI I2C interrupt flags (IFG) are set and an automatic flag-clearing event on the I2C bus occurs, the program counter may become corrupted. This will only happen when the IFG is cleared within a critical time window (~6 CPU clock cycles) after a USCI interrupt request occurs and before the interrupt servicing is initiated. The affected interrupts are UCBxTXIFG, UCSTPIFG, UCSTTIFG and UCNACKIFG.

The automatic flag-clearing scenarios are described in the following situations:

(1) A pending UCBxTXIFG interrupt request is cleared on the falling SCL clock edge following a NACK.

(2) A pending UCSTPIFG, UCSTTIFG, or UCNACKIFG interrupt request is cleared by a following Start condition.

Workaround (1) Polling the affected flags instead of enabling the interrupts.

or

(2) Ensuring the above mentioned flag-clearing events occur after a time delay of 6 CPU clock cycles has elapsed since the interrupt request occurred and was accepted.

USCI30 *USCI Module*

Function I2C mode master receiver / slave receiver

Description When the USCI I2C module is configured as a receiver (master or slave), it performs a double-buffered receive operation. In a transaction of two bytes, once the first byte is moved from the receive shift register to the receive buffer the byte is acknowledged and the state machine allows the reception of the next byte.

If the receive buffer has not been cleared of its contents by reading the UCBxRXBUF register while the 7th bit of the following data byte is being received, an error condition may occur on the I2C bus. Depending on the USCI configuration the following may occur:

1) If the USCI is configured as an I2C master receiver, an unintentional repeated start condition can be triggered or the master switches into an idle state (I2C communication aborted). The reception of the current data byte is not successful in this case.

2) If the USCI is configured as I2C slave receiver, the slave can switch to an idle state

stalling I2C communication. The reception of the current data byte is not successful in this case. The USCI I2C state machine will notify the master of the aborted reception with a NACK.

Note that the error condition described above occurs only within a limited window of the 7th bit of the current byte being received. If the receive buffer is read outside of this window (before or after), then the error condition will not occur.

Workaround

a) The error condition can be avoided altogether by servicing the UCBxRXIFG in a timely manner. This can be done by (a) servicing the interrupt and ensuring UCBxRXBUF is read promptly or (b) Using the DMA to automatically read bytes from receive buffer upon UCBxRXIFG being set.

OR

b) In case the receive buffer cannot be read out in time, test the I2C clock line before the UCBxRXBUF is read out to ensure that the critical window has elapsed. This is done by checking if the clock line low status indicator bit UCSCLLOW is set for atleast three USCI bit clock cycles i.e. 3 X t(BitClock).

Note that the last byte of the transaction must be read directly from UCBxRXBUF. For all other bytes follow the workaround:

Code flow for workaround

(1) Enter RX ISR for reading receiving bytes

(2) Check if UCSCLLOW.UCBxSTAT == 1

(3) If no, repeat step 2 until set

(4) If yes, repeat step 2 for a time period > 3 x t (BitClock) where t (BitClock) = 1/ f (BitClock)

(5) If window of 3 x t(BitClock) cycles has elapsed, it is safe to read UCBxRXBUF

USCI35 *USCI Module*

Function Violation of setup and hold times for (repeated) start in I2C master mode

Description In I2C master mode, the setup and hold times for a (repeated) START, $t_{SU,STA}$ and $t_{HD,STA}$ respectively, can be violated if SCL clock frequency is greater than 50kHz in standard mode (100kbps). As a result, a slave can receive incorrect data or the I2C bus can be stalled due to clock stretching by the slave.

Workaround If using repeated start, ensure SCL clock frequencies is < 50kHz in I2C standard mode (100 kbps).

XOSC5 *XOSC Module*

Function LF crystal failures may not be properly detected by the oscillator fault circuitry

Description The oscillator fault error detection of the LFXT1 oscillator in low frequency mode (XTS = 0) may not work reliably causing a failing crystal to go undetected by the CPU, i.e. OFIFG will not be set.

Workaround None

XOSC6 *XOSC Module*

Function XT2 crystal failures may not be properly detected by the oscillator fault circuitry

Description The XT2OF flag should be set if the XT2 frequency falls below 30kHz. If there is no oscillation at all, the flag will still operate properly. However, 0-30kHz produces an undefined state on XT2OF. When this occurs, OFIFG will not be set.

Workaround Do not depend on the fault detection circuitry to accurately detect all failures.

XOSC8 *XOSC Module*

Function ACLK failure when crystal ESR is below 40 kOhm.

Description When ACLK is sourced by a low frequency crystal with an ESR below 40 kOhm, the duty cycle of ACLK may fall below the specification; the OFIFG may become set or in some instances, ACLK may stop completely.

Workaround Please refer to "XOSC8 Guidance" found at SLAA423 for information regarding working with this erratum.

4 Document Revision History

Changes from family erratasheet to device specific erratasheet.

1. Errata CPU19 was removed
2. Description for TAB22 was updated
3. Function for BCL13 was updated
4. ADC19 is impacting silicon Revision A

Changes from device specific erratasheet to document Revision A.

1. Errata BCL15 was added to the errata documentation.

Changes from document Revision A to Revision B.

1. BCL12 Workaround was updated.

Changes from document Revision B to Revision C.

1. Errata TA21 was added to the errata documentation.

Changes from document Revision C to Revision D.

1. Errata TB24 was added to the errata documentation.

Changes from document Revision D to Revision E.

1. Errata USCI35 was added to the errata documentation.

Changes from document Revision E to Revision F.

1. Errata JTAG23 was added to the errata documentation.

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